

eGRAF HiTherm™ Thermal Interface

High performance materials formulated for use with today's high power components which require minimal thermal resistance for maximum heat transfer efficiency.

eGraf™ HiTherm thermal interface products provide phase change-like performance without the reflow or rework issue of phase change materials.

Advancements

- 40% improvement in thermal conductivity
- 45% reduction in thermal resistance

Available in: (rolls and cut sheets)

0.003" (.0762 mm) 0.005" (.127 mm) 0.010" (.254 mm)

Graftech, striving to deliver new solutions to meet increasingly demanding heat management requirements of the electronics industry.

GRAFTECH

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